

**LMP3415ZF 20V P-Channel Enhancement MOSFET****Features**

- $R_{DS(ON)} = 45\text{m}\Omega @ V_{GS} = -4.5\text{V}$
- $R_{DS(ON)} = 58\text{m}\Omega @ V_{GS} = -2.5\text{V}$
- $R_{DS(ON)} = 85\text{m}\Omega @ V_{GS} = -1.8\text{V}$
- Super high density cell design for extremely low  $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- SOT-23 package design

These devices are particularly suited for low Voltage power management, such as smart Phone and notebook computer and other battery powered circuits, and low in-line power loss are needed in commercial industrial surface mount applications.

**Product Description**

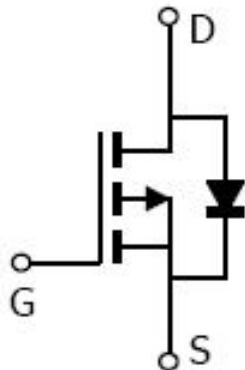
LMP3415ZF, P-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent  $R_{DS(ON)}$ , low gate charge.

**Applications**

- Portable Equipment
- Battery Powered System
- Net Working System

**Pin Configuration**

<b>LMP3415ZF (SOT-23)</b>	
<b>Top Views</b>	
<b>Pin</b>	<b>Description</b>
1	Gate
2	Source
3	Drain



**Ordering Information**

Part Number	P/N	PKG Code	Pb Free Code	Package	Quantity Reel
LMP3415ZF	LMP3415	Z	F	SOT-23	3000 pcs

**Marking Information**

Part Marking	Part Number	LFC code
15 XW	15	XW

**Absolute Maximum Ratings**(T<sub>A</sub>=25°C Unless otherwise noted)

Symbol	Parameter		Typical	Unit
V <sub>DSS</sub>	Drain-Source Voltage		-20	V
V <sub>GSS</sub>	Gate-Source Voltage		±12	V
I <sub>D</sub>	Continuous Drain Current	T <sub>A</sub> =25°C	-4.9	A
		T <sub>A</sub> =70°C	-3.9	
I <sub>DM</sub>	Pulsed Drain Current		-10	A
I <sub>S</sub>	Continuous Body Diode Forward Current		-1.6	A
P <sub>D</sub>	Total Power Dissipation	T <sub>A</sub> =25°C	1.56	W
		T <sub>A</sub> =70°C	1.0	
T <sub>J</sub>	Operating Junction Temperature		-55 to +150	°C
T <sub>STG</sub>	Storage Temperature Range		-55 to +150	°C
R <sub>θJA</sub>	Thermal Resistance-Junction to Ambient		80	°C/W

### Electrical Characteristics

(T<sub>A</sub>=25°C Unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =-250uA	-20			V
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250uA	-0.4		-0.9	V
I <sub>GSS</sub>	Gate Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±12V			±100	nA
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =-16V, V <sub>GS</sub> =0V			-1	uA
		V <sub>DS</sub> =-16V, V <sub>GS</sub> =0V, T <sub>J</sub> =85°C			-10	
R <sub>DS(on)</sub>	Drain-Source On-Resistance	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-4.9A		40	45	mΩ
		V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-3.4A		50	58	
		V <sub>GS</sub> =-1.8V, I <sub>D</sub> =-2.2A		60	85	
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =-5V, I <sub>D</sub> =-3.6A		10		S
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =-1.6A		-0.85	-1.2	V
<b>Dynamic</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =-10V, V <sub>GS</sub> =0V, f=1MHz		1050		pF
C <sub>oss</sub>	Output Capacitance			165		
C <sub>rss</sub>	Reverse Transfer Capacitance			135		
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =-10V, V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-4.0A		10	18	nC
Q <sub>gs</sub>	Gate-Source Charge			2.5		
Q <sub>gd</sub>	Gate-Drain Charge			3.5		
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =-10V, I <sub>D</sub> =-3.7A, V <sub>GS</sub> =-4.5V, R <sub>L</sub> =2.7Ω, R <sub>G</sub> =1Ω		15	25	ns
T <sub>r</sub>	Turn-On Rise Time			25	40	
t <sub>d(off)</sub>	Turn-Off Delay Time			40	65	
T <sub>f</sub>	Turn-Off Fall Time			15	25	

### Typical Performance Characteristics

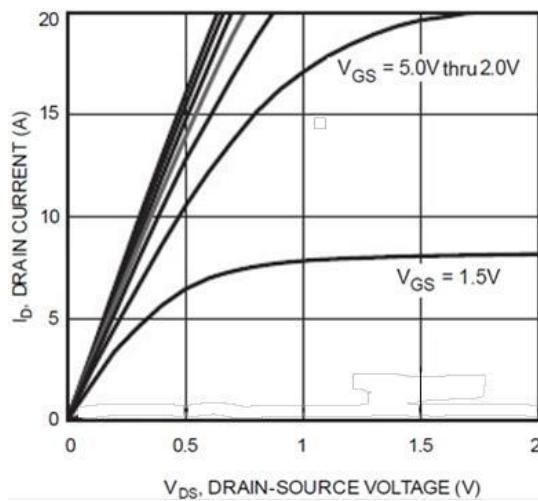


Fig.1 Typical Output Characteristics

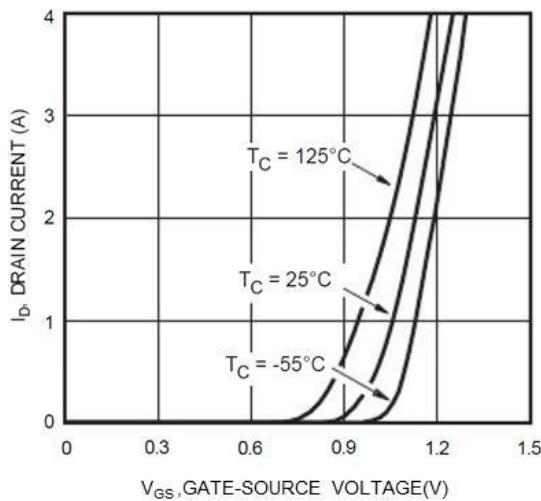


Fig.2 Typical Transfer Characteristics

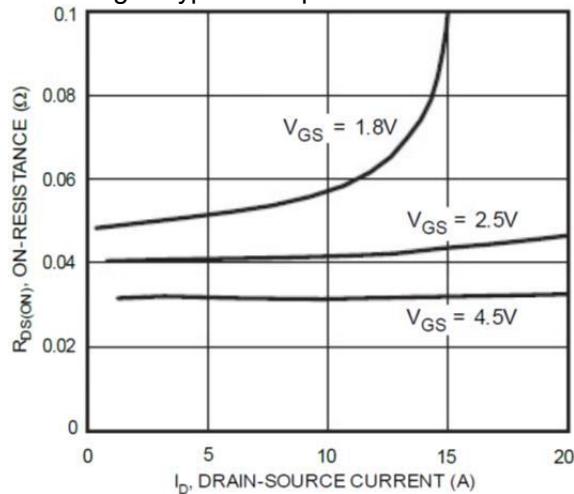


Fig.3 On-Resistance vs. Drain Current

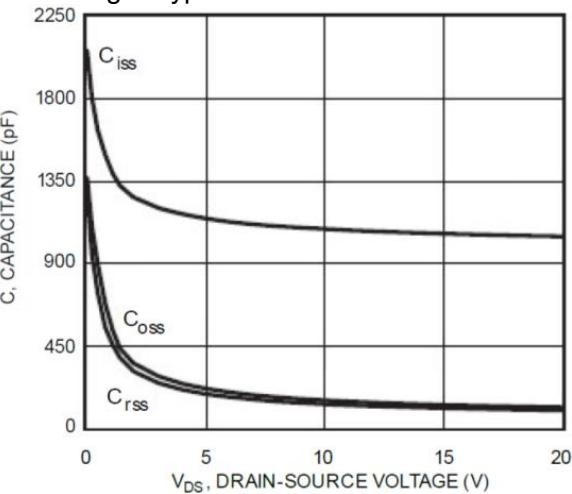


Fig.4 Capacitance vs. Drain-Source Voltage

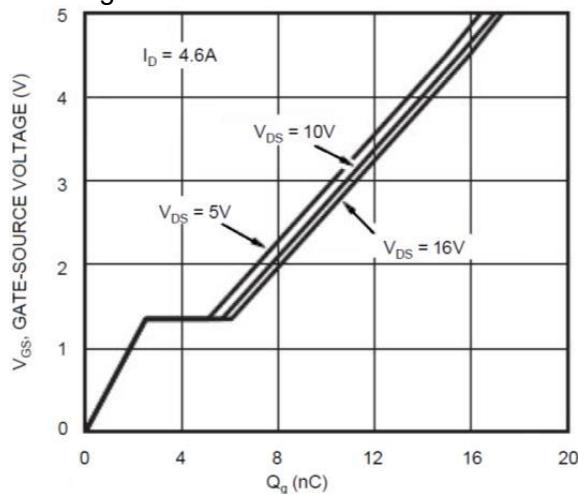


Fig.5 Gate Charge

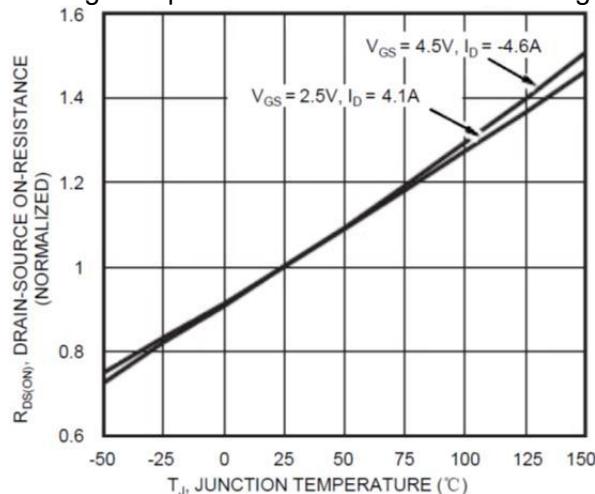
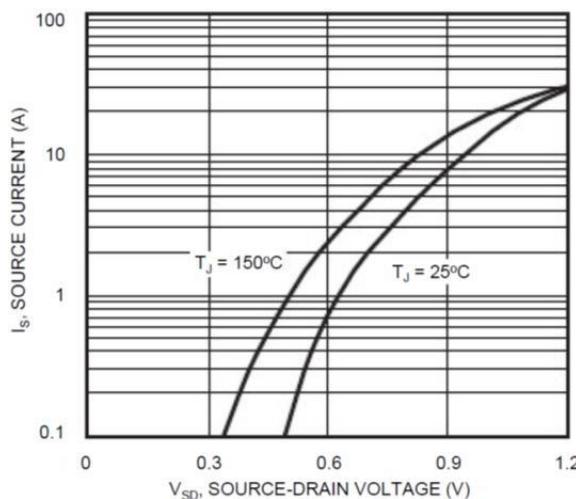
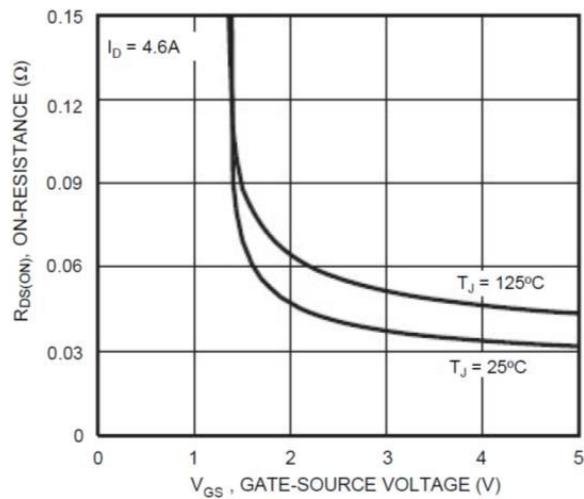
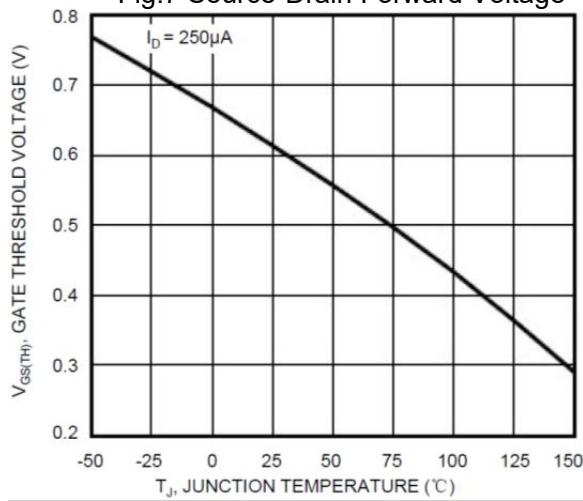
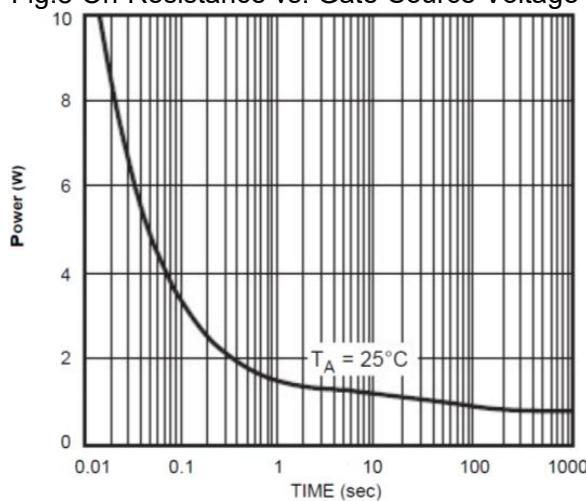
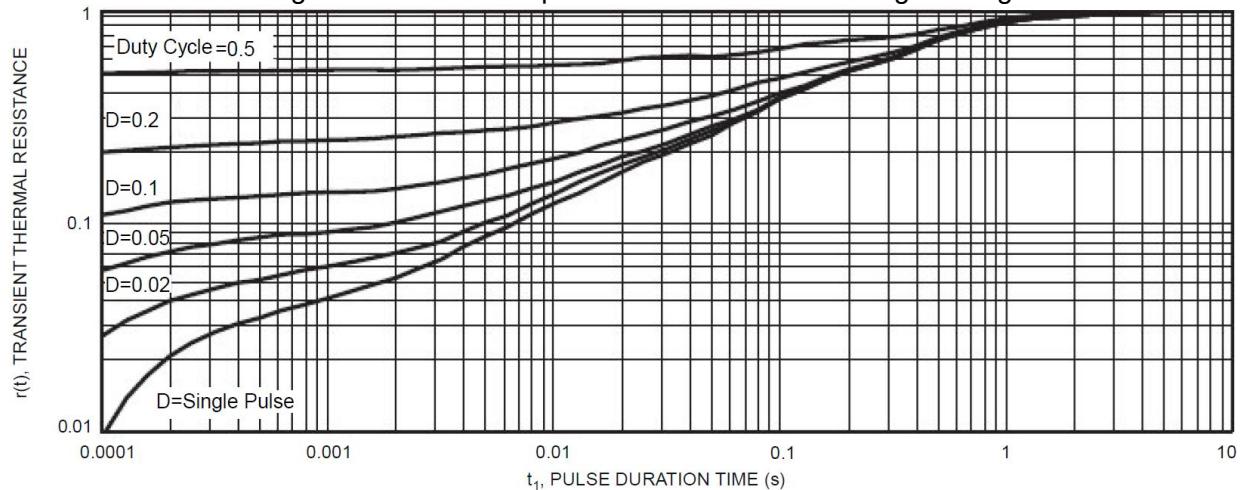
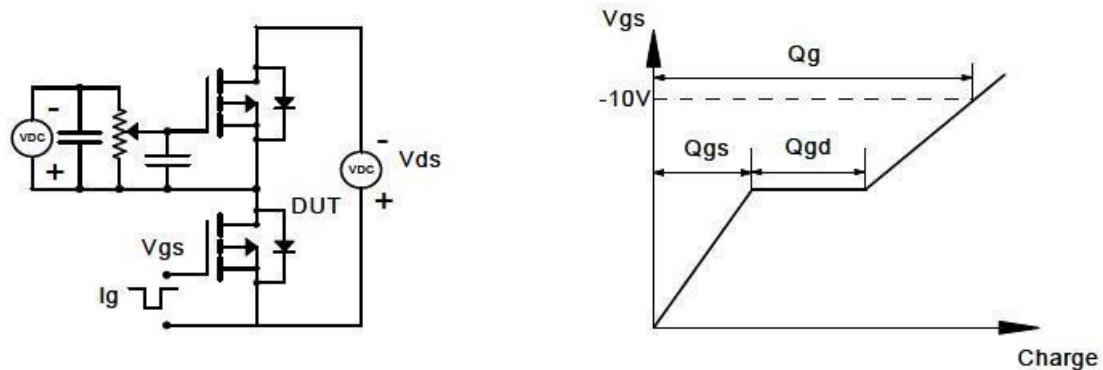
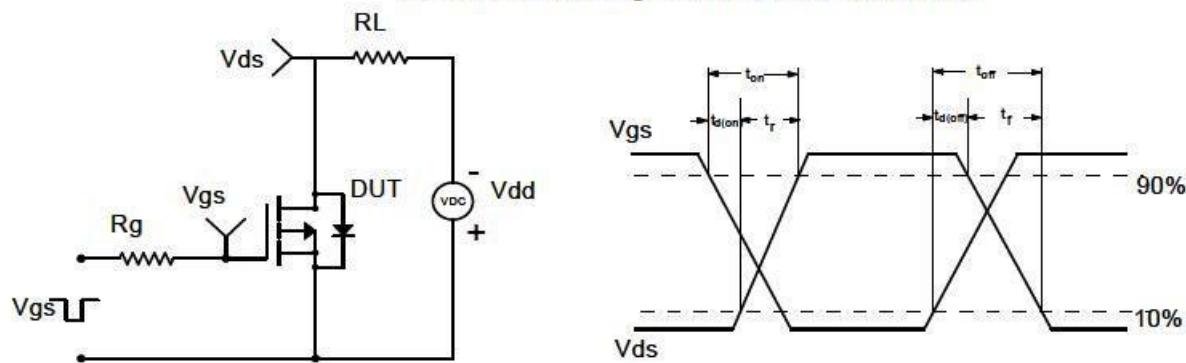
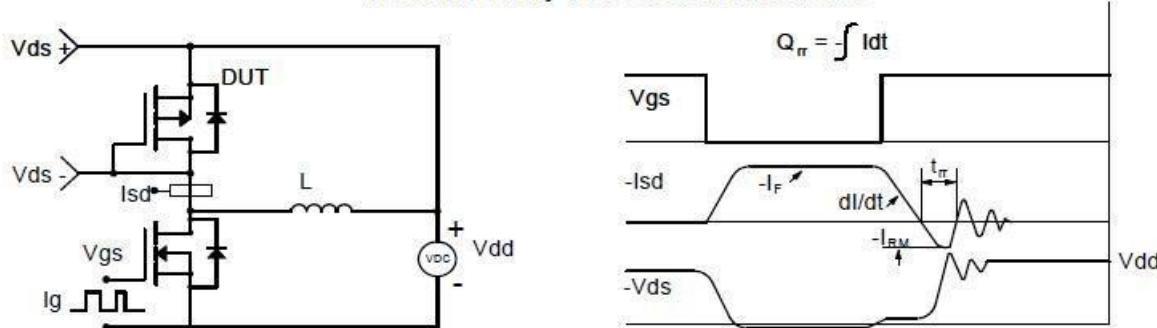
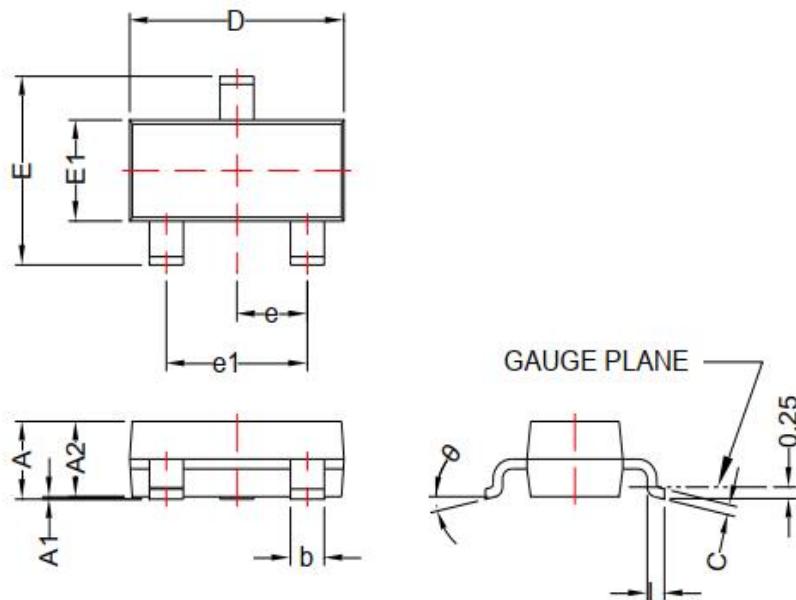


Fig.6 On-Resistance vs. Junction Temperature

**Typical Performance Characteristics (continue.)**

**Fig.7 Source-Drain Forward Voltage**

**Fig.8 On-Resistance vs. Gate-Source Voltage**

**Fig.9 Gate Threshold Voltage vs. Junction Temperature**

**Fig.10 Single Pulse Power**

**Fig.11 Normalized Thermal Transient Impedance**

**Typical Performance Characteristics (continue.)**
**Gate Charge Test Circuit & Waveform**

**Resistive Switching Test Circuit & Waveforms**

**Diode Recovery Test Circuit & Waveforms**


**Package Dimension**
**SOT-23**


Dimensions				
Symbol	Millimeters		Inches	
	Min	Max	Min	Max
<b>A</b>	0.750	1.170	0.030	0.046
<b>A1</b>	0.010	0.150	0.000	0.006
<b>A2</b>	0.700	1.020	0.028	0.040
<b>b</b>	0.300	0.500	0.012	0.020
<b>c</b>	0.080	0.200	0.003	0.008
<b>D</b>	2.800	3.040	0.110	0.120
<b>E</b>	2.100	2.640	0.083	0.104
<b>E1</b>	1.200	1.400	0.047	0.055
<b>e</b>	0.950 BSC		0.037 BSC	
<b>e1</b>	1.900 BSC		0.075 BSC	
<b>L</b>	0.300	0.600	0.012	0.024
<b>θ</b>	0°	8°	0°	8°